

Bill of Materials

TI DESIGNS
TIDA-00330 - Reinforced Isolated M-LVDS Transceiver

Item	Quantity	Reference	Part	Footprint	Manufacturer	Manufacturer Part Number
1	1	C1	1uF	0402	Taiyo Yuden	LMK105BJ105KV-F
2	2	C2, C3	1uF	0603	TDK	C1608X7R1C105K
3	1	C4	4.7uF	0603	TDK	C1608X5R0J475K
4	2	C5, C6, C7	0.1uF	0603		
5	2	D1, D2	MBR0520L	SOD-123	ON-Semi	MBR0520LT1G
6	6	J1, J2, J3, J4, J5, J6	SMA_END_JACK_RND		Johnson Components	142-0701-801
7	4	JMP1, JMP2, JMP3, JMP4	Header 3x1			
8	1	R1	50	0603		
9	1	R2	100	0603		
10	1	R3	DNI	0603		
11	1	R4	0	0603		
12	2	R5, R6	4.7k	0603		
13	2	R7, R8	1k	0603		
14	1	T1	1:1.3	SMT	Würth Electronics	750313638
15	1	TB1	Terminal Block 1x2			
16	1	U1	ISO7842	16DW	Texas Instruments	ISO7842DW
17	1	U2	SN65MLVD203	SOIC-14	Texas Instruments	SN65MLVD203DR
18	1	U3	SN6501	SOT-23	Texas Instruments	SN6501DBVR
19	1	U4	TPS76333	SOT-23	Texas Instruments	TPS76333DBVR

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